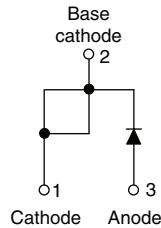


HEXFRED® Ultrafast Soft Recovery Diode, 8 A


TO-220AC

FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Lead (Pb)-free
- Designed and qualified for industrial level



Available
RoHS*
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA08TB120 is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A continuous current, the HFA08TB120 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08TB120 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R	1200 V
V_F at 8 A at 25 °C	3.3 V
$I_{F(AV)}$	8 A
t_{rr} (typical)	28 ns
T_J (maximum)	150 °C
Q_{rr} (typical)	140 nC
$dI_{(rec)M}/dt$ (typical) at 125 °C	85 A/ μ s
I_{RRM} (typical)	4.5 A

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	8	A
Single pulse forward current	I_{FSM}		130	
Maximum repetitive forward current	I_{FRM}		32	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	73.5	W
		$T_C = 100\text{ °C}$	29	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

* Pb containing terminations are not RoHS compliant, exemptions may apply

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 µA	1200	-	-	V
Maximum forward voltage	V _{FM}	I _F = 8.0 A	-	2.6	3.3	
		I _F = 16 A	-	3.4	4.3	
		I _F = 8.0 A, T _J = 125 °C	-	2.4	3.1	
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	-	0.31	10	µA
		T _J = 125 °C, V _R = 0.8 x V _R rated	-	135	1000	
Junction capacitance	C _T	V _R = 200 V	-	11	20	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 1.0 A, dI _F /dt = 200 A/µs, V _R = 30 V	-	28	-	ns
	t _{rr1}	T _J = 25 °C	-	63	95	
	t _{rr2}	T _J = 125 °C	-	106	160	
Peak recovery current	I _{RRM1}	T _J = 25 °C	-	4.5	8.0	A
	I _{RRM2}	T _J = 125 °C	-	6.2	11	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C	-	140	380	nC
	Q _{rr2}	T _J = 125 °C	-	335	880	
Peak rate of recovery current during t _b	dI _(rec) /dt1	T _J = 25 °C	-	133	-	A/µs
	dI _(rec) /dt2	T _J = 125 °C	-	85	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	1.7	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC	HFA08TB120			

HEXFRED® Ultrafast Soft Recovery Diode, 8 A

Vishay High Power Products

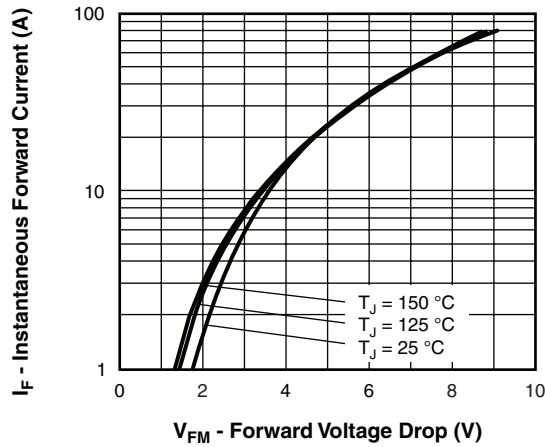


Fig. 1 - Maximum Forward Voltage Drop Characteristics

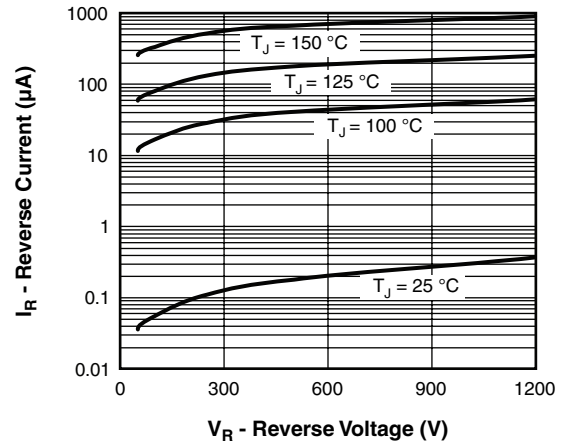


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

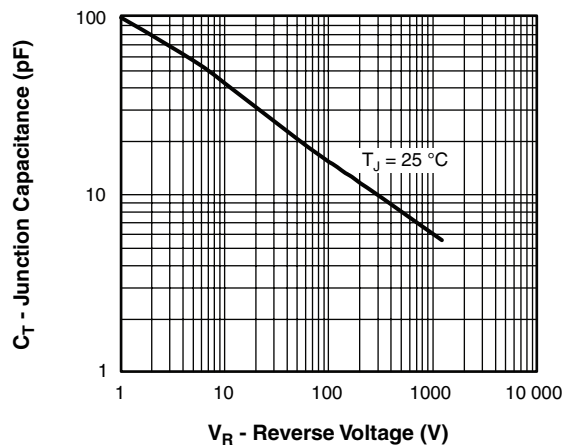


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

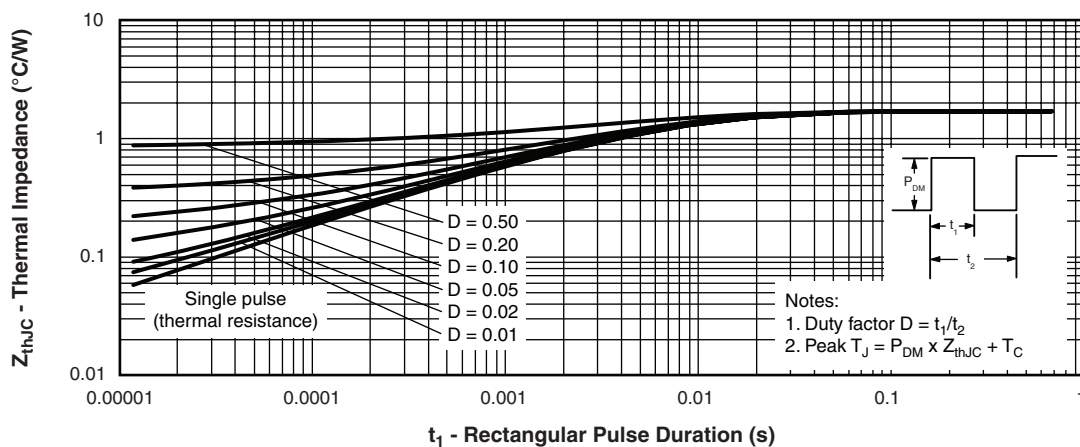
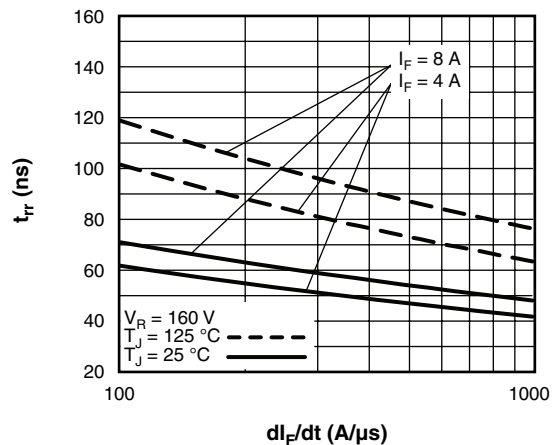
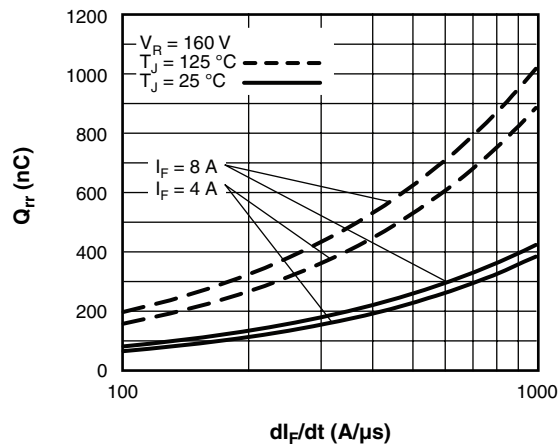
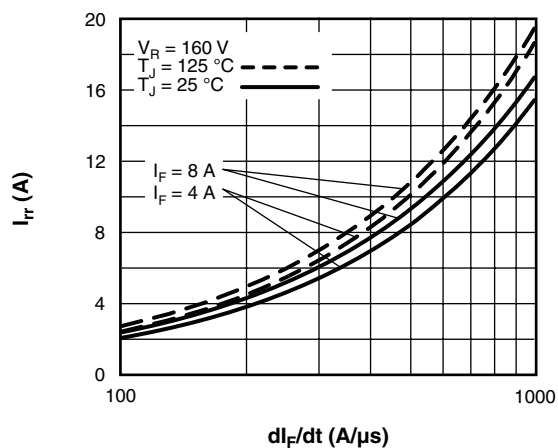
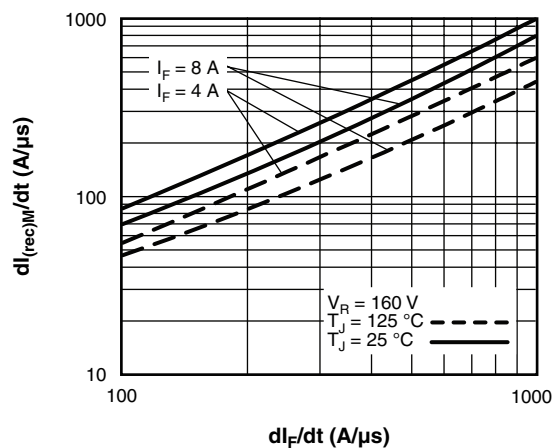


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt Fig. 7 - Typical Stored Charge vs. dI_F/dt Fig. 6 - Typical Recovery Current vs. dI_F/dt Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

HEXFRED®
Ultrafast Soft Recovery Diode, 8 A

Vishay High Power Products

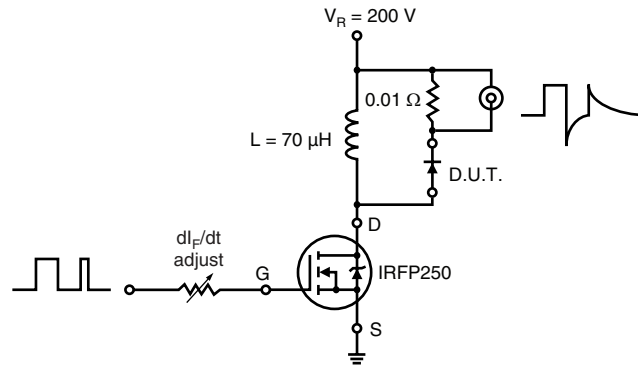


Fig. 9 - Reverse Recovery Parameter Test Circuit

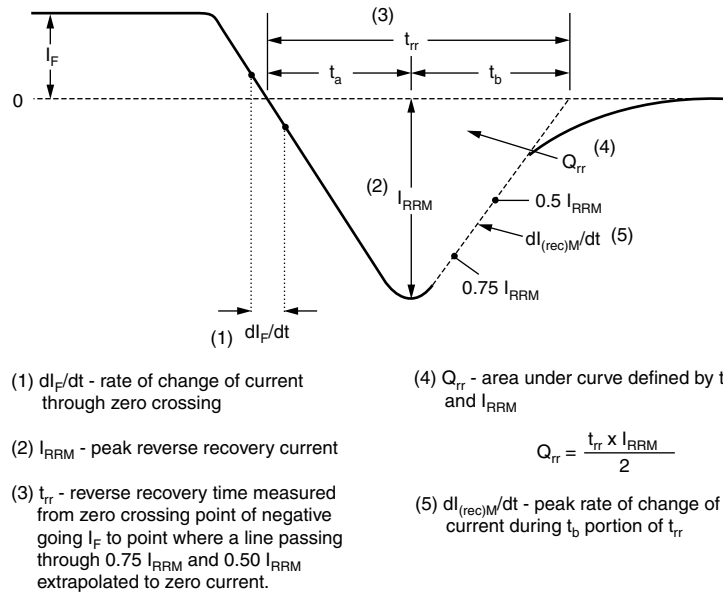


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	HF	A	08	TB	120	PbF
	1	2	3	4	5	6

- | | | |
|----------|---|--|
| 1 | - | HEXFRED® family |
| 2 | - | Process designator A = subs. elec. irradi.
B = subs. platinum |
| 3 | - | Current rating (08 = 8 A) |
| 4 | - | Package outline (TB = TO-220, 2 leads) |
| 5 | - | Voltage rating (120 = 1200 V) |
| 6 | - | • None = Standard production
• PbF = Lead (Pb)-free |

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95221
Part marking information	http://www.vishay.com/doc?95224



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.